

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method of labeling a semiconductor device component, comprising:  
~~the at least partially selectively~~ consolidating unconsolidated material over a surface of at least one substrate ~~the to at least a semisolid state~~ to form at least a portion of a mark over the surface.
2. (Previously presented) The method of claim 23, wherein disposing comprises disposing at least one layer of an uncured polymer.
3. (Currently amended) The method of claim 2, wherein ~~at least partially selectively~~ consolidating comprises at least partially curing polymer at the plurality of selected areas.
4. (Previously presented) The method of claim 2, wherein disposing comprises disposing at least one layer of an uncured photopolymer.
5. (Currently amended) The method of claim 4, wherein ~~at least partially selectively~~ consolidating comprises at least partially curing photopolymer at the plurality of selected areas.
6. (Previously presented) The method of claim 5, wherein at least partially curing comprises directing a UV laser over the plurality of selected areas of the at least one layer.
7. (Previously presented) The method of claim 6, wherein at least partially curing comprises curing at least edges of the corresponding layer of the mark.

8. (Previously presented) The method of claim 7, further comprising further curing uncured photopolymer bounded by the edges.
9. (Previously presented) The method of claim 8, wherein further curing comprises thermally curing the uncured photopolymer.
10. (Previously presented) The method of claim 8, wherein further curing comprises subjecting the uncured photopolymer to UV radiation.
11. (Previously presented) The method of claim 7, wherein curing at least edges comprises curing at least an outer periphery of the mark.
12. (Previously presented) The method of claim 11, wherein curing at least edges further comprises curing an inner periphery of the mark.
13. (Previously presented) The method of claim 26, wherein sequentially consolidating comprises sequentially consolidating a plurality of superimposed, contiguous layers of unconsolidated material and securing adjacent ones of the plurality of layers to one another.
14. (Previously presented) A method of labeling a semiconductor device component, comprising:  
placing at least one substrate in a horizontal plane; and  
selectively consolidating material to form at least one mark on the at least one substrate.
15. (Previously presented) The method of claim 14, wherein selectively consolidating comprises:  
disposing a layer comprising unconsolidated material on the at least one substrate; and  
at least partially consolidating unconsolidated material in a plurality of selected regions of the layer in a sequential fashion.

16. (Previously presented) The method of claim 15, wherein selectively consolidating further comprises:  
repeating the disposing and the at least partially consolidating at least once.

17. (Previously presented) The method of claim 14, further comprising:  
recognizing a location and an orientation of the at least one substrate.

18. (Previously presented) The method of claim 17, further comprising storing data including at least one physical parameter of the at least one substrate and of the at least one mark in computer memory and using the stored data in conjunction with a machine vision system to recognize the location and the orientation of the at least one substrate.

19. (Previously presented) The method of claim 18, further comprising storing in computer memory at least one parameter of another structure to be associated with the at least one substrate.

20. (Previously presented) The method of claim 18, further comprising using the stored data, in conjunction with the machine vision system, to effect selectively consolidating material to form the at least one mark.

21. (Previously presented) The method of claim 17, further comprising recognizing the location of the at least one substrate on which the at least one mark is to be fabricated.

22. (Previously presented) The method of claim 17, further comprising securing the at least one substrate to a carrier prior to placing the at least one substrate in the horizontal plane.

23. (Previously presented) The method of claim 1, further comprising:  
disposing at least one layer of the unconsolidated material over the surface of the at least one substrate.

24. (Previously presented) The method of claim 23, wherein at least partially consolidating comprises at least partially consolidating the unconsolidated material at a plurality of selected areas of the at least one layer to form a corresponding layer of the mark.

25. (Previously presented) The method of claim 1, wherein at least partially consolidating is effected under control of a program.

26. (Previously presented) The method of claim 1, wherein at least partially consolidating comprises forming a plurality of adjacent, mutually adhered regions of the mark.